

Title (en)

MOLDED ARTICLE FOR HOLDING WAFER

Publication

EP 0436030 A4 19920812 (EN)

Application

EP 90910186 A 19900704

Priority

- JP 9000863 W 19900704
- JP 17679589 A 19890707

Abstract (en)

[origin: EP0436030A1] A molded article for holding a wafer, which is made of a thermoplastic resin reinforced with whiskers and used for handling a wafer and a glass sheet for a liquid crystal television set, such as a transfer basket, a storage case, a carrier jig, and the like. It is useful for washing, drying, moving or storing a semiconductor wafer free of contamination. <IMAGE>

IPC 1-7

H01L 21/68

IPC 8 full level

B65D 85/86 (2006.01); **C08K 7/08** (2006.01); **C08K 9/02** (2006.01); **C08L 23/10** (2006.01); **H01L 21/673** (2006.01); **H01L 21/68** (2006.01)

CPC (source: EP US)

H01L 21/67366 (2013.01 - EP US); **H01L 21/6835** (2013.01 - EP US); **Y10S 428/902** (2013.01 - EP US); **Y10S 428/931** (2013.01 - EP US); **Y10T 428/1314** (2015.01 - EP US); **Y10T 428/1372** (2015.01 - EP US)

Citation (search report)

- [A] WO 8902860 A1 19890406 - NCR CO [US]
- [AP] US 4881642 A 19891121 - ADAM WILLIAM D [US]
- See references of WO 9101044A1

Cited by

EP1724825A1; EP0971000A4; EP1429380A4; FR2679524A1; US7781035B2

Designated contracting state (EPC)

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